

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>TIAN-CHOY GAN</td> <td>01/10/2014</td> </tr> <tr> <td>HSIEN-CHIN LIN</td> <td>11/22/2013</td> </tr> <tr> <td>CHIA-PIN LIN</td> <td>11/22/2013</td> </tr> <tr> <td>SHYUE-SHYH LIN</td> <td>11/22/2013</td> </tr> <tr> <td>LI-SHIUN CHEN</td> <td>12/03/2013</td> </tr> <tr> <td>SHIN HSIEN LIAO</td> <td>12/11/2013</td> </tr> </tbody> </table>		Name	Execution Date	TIAN-CHOY GAN	01/10/2014	HSIEN-CHIN LIN	11/22/2013	CHIA-PIN LIN	11/22/2013	SHYUE-SHYH LIN	11/22/2013	LI-SHIUN CHEN	12/03/2013	SHIN HSIEN LIAO	12/11/2013
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8, LI-HSIN RD. 6</td> </tr> <tr> <td>Internal Address:</td> <td>SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8, LI-HSIN RD. 6	Internal Address:	SCIENCE-BASED INDUSTRIAL PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77		
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Application Number:	14083533														
CORRESPONDENCE DATA															
Fax Number:	(214)200-0853														
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<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
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PATENT

NAME OF SUBMITTER:	LYDIA EPPS-HILLIARD
Signature:	/Lydia Epps-Hilliard/
Date:	01/22/2014
Total Attachments: 3 source=2706_Assignment#page1.tif source=2706_Assignment#page2.tif source=2706_Assignment#page3.tif	

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|--|
| (1) | Tian-Choy Gan | of | 13F.-3, No. 66, Liujia 7 th Road
Zhubei City, Hsinchu County 302
Taiwan, R.O.C. |
| (2) | Hsien-Chin Lin | of | 18F., No. 149, Guanxin N. Road
East District, Hsinchu City 300
Taiwan, R.O.C. |
| (3) | Chia-Pin Lin | of | No. 32, Sec. 1, Yangxin Road
Xinpu Township, Hsinchu County 305
Taiwan, R.O.C. |
| (4) | Shyue-Shyh Lin | of | 12F., No. 133, Sec. 2, Jiafeng 5 th Road
Zhubei City, Hsinchu County 302
Taiwan, R.O.C. |
| (5) | Li-Shiun Chen | of | 2F, No. 27, Alley 16, Lane 354
Kuang-Fu Road, Section 1
HsinChu, Taiwan, R.O.C. |
| (6) | Shin Hsien Liao | of | No. 68-14, Fongshou Village
Minsyong Township, Chiayi County 621
Taiwan, R.O.C. |

have invented certain improvements in

HYBRID GATE PROCESS FOR FABRICATING FINFET DEVICE

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
X filed on November 19, 2013 and assigned application number 14/083,533; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications

thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Tian-Choy Gan

Residence Address: 13F.-3, No. 66, Liujia 7th Road
Zhubei City, Hsinchu County 302 Taiwan, R.O.C.

✓ Dated: 01/10/2014

✓ Tian-Choy Gan
Inventor Signature

Inventor Name: Hsien-Chin Lin

Residence Address: 18F., No. 149, Guanxin N. Road, East District
Hsinchu City 300 Taiwan, R.O.C.

Dated: 11/22/2013

Hsien-Chin Lin
Inventor Signature

Inventor Name: Chia-Pin Lin

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Xinpu Township, Hsinchu County 305 Taiwan, R.O.C.

Dated: 11/22/2013

Chia-Pin Lin
Inventor Signature

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Dated: 11/22/13

Shyue-Shyh Lin
Inventor Signature

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Dated: 12/3/2013

Li-Shium Chen
Inventor Signature

Inventor Name: Shin Hsien Liao

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Dated: 12/11/2013

Shin Hsien Liao
Inventor Signature